

09/998241

ABSTRACT OF THE DISCLOSURE

A direct attachment technique is described for silicon packages housing high frequency devices. A silicon package may be shaped as either a plug or a socket or the package may have both the plug and socket capability, thus enabling the package to be directly attached to other packages. The plug is trapezoidal in cross section while the socket has a dovetail-joint-like aperture. The plug is inserted into the socket thereby directly attaching one package to another. The two packages are locked together when the slanted edges of the plug are fitted to the slanted edges of the socket.

SECRET F428660